



# P-Channel 150-V (D-S) MOSFET

PRODU	CT SUMMARY		
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)
- 150	1.2 at V <sub>GS</sub> = - 10 V	- 0.69	7.7
- 150	1.3 at V <sub>GS</sub> = - 6.0 V	- 0.66	· · · ·

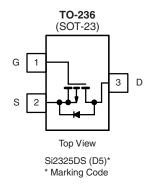
### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET<sup>®</sup> Power MOSFET
- Ultra Low On-Resistance
- Small Size



#### **APPLICATIONS**

• Active Clamp Circuits in DC/DC Power Supplies



Ordering Information: Si2325DS -T1-E3 (Lead (Pb)-free)

Si2325DS -T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS T	<sub>A</sub> = 25 °C, unle	ss otherwise r	noted		
Parameter		Symbol	5 s	Steady State	Unit
Drain-Source Voltage		V <sub>DS</sub>	- 150		V
Gate-Source Voltage		$V_{GS}$	± 20		V
Continuous Proin Comment /T 150 °C) a b	T <sub>A</sub> = 25 °C	1	- 0.69	- 0.53	
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a, b</sup>	T <sub>A</sub> = 70 °C	I <sub>D</sub>	- 0.55	- 0.43	
Pulsed Drain Current		I <sub>DM</sub>	- 1.6		Α
Continuous Source Current (Diode Conduction) <sup>a, b</sup>		I <sub>S</sub>	- 1.0	- 0.6	
Single Pulse Avalanche Current	ralanche Current L = 1.0 mH		4.5		
Single Pulse Avalanche Energy	L = 1.0 mm	E <sub>AS</sub>	1.01		mJ
Mariana Barra Birata da h	T <sub>A</sub> = 25 °C	P <sub>D</sub>	1.25	0.75	W
Maximum Power Dissipation <sup>a, b</sup>	T <sub>A</sub> = 70 °C	' D	0.8	0.48	۷V
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maniana Institut to Analisma	t ≤ 5 s	<b>D</b>	75	100	°C/W
Maximum Junction-to-Ambient <sup>a</sup>	Steady State	$R_{thJA}$	120	166	
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	40	50	

### Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. Pulse width limited by maximum junction temperature.

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			Limits				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 150			V	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = -250 \mu A$	- 2.5		- 4.5	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zoro Cata Valtaga Drain Current	l	V <sub>DS</sub> = - 150 V, V <sub>GS</sub> = 0 V			- 1	4	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 150 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 10	μΑ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -15 \text{ V}, V_{GS} = 10 \text{ V}$	- 1.6			Α	
	D	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 0.5 A		1.0	1.2	0	
Drain-Source On-Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 6.0 V, I <sub>D</sub> = - 0.5 A		1.05	1.3	Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 0.5 A		2.2		S	
Diode Forward Voltage	$V_{SD}$	I <sub>S</sub> = - 1.0 A, V <sub>GS</sub> = 0 V		0.7	- 1.2	٧	
Dynamic <sup>b</sup>			•	•			
Total Gate Charge	$Q_g$	V 75 V V 10 V		7.7	12		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = -75 \text{ V}, V_{GS} = 10 \text{ V},$ $I_{D} \cong -0.5 \text{ A}$		1.5		nC	
Gate-Drain Charge	$Q_{gd}$	1D = - 0.3 A		2.5			
Gate Resistance	$R_g$	f = 1.0 MHz		9		Ω	
Input Capacitance	C <sub>iss</sub>			340	510		
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		30		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			16		1	
Switching <sup>c</sup>							
Time On Time	t <sub>d(on)</sub>	V <sub>DD</sub> = - /5 V B <sub>1</sub> = /5 ()	7	11			
Turn-On Time	t <sub>r</sub>			11	17	ns	
Turn-Off Time	t <sub>d(off)</sub>	$R_{a} = 6 \Omega$		16	25	115	
Turn-On Time	t <sub>f</sub>	· ·y		11	17		
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	$I_F = 0.5 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$		90	135	nC	

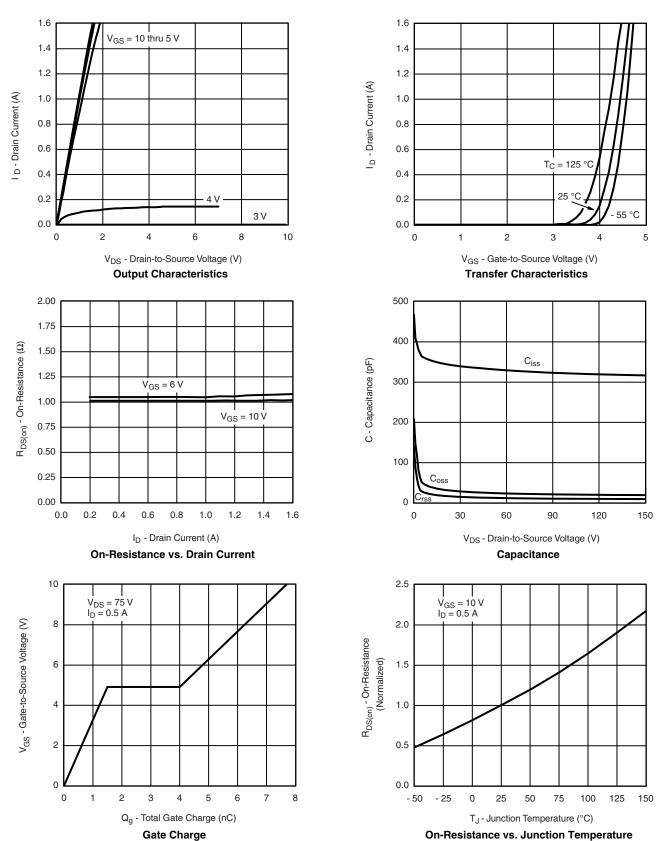
## Notes:

- a. Pulse test: PW  $\leq$  300  $\mu s$  duty cycle  $\leq$  2 %.
- b. For DESIGN AID ONLY, not subject to production testing.
- c. Switching time is essentially independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



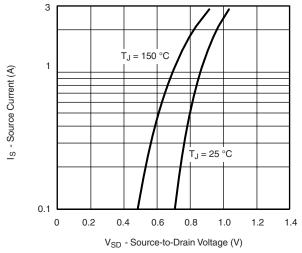
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



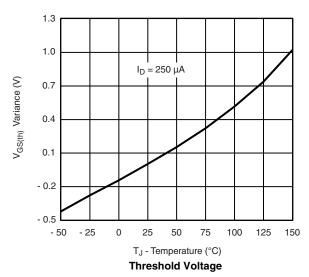
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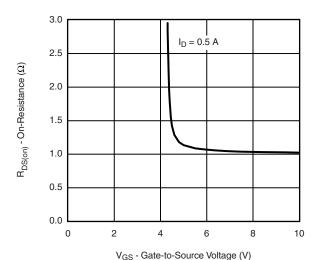
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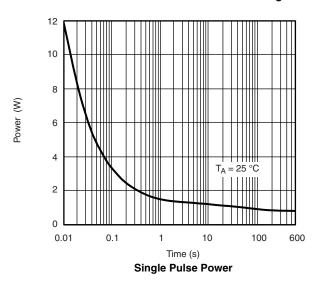


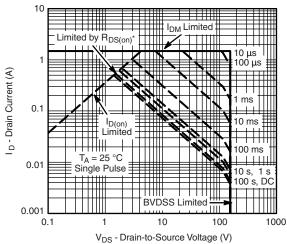
### Source-Drain Diode Forward Voltage





On-Resistance vs. Gate-to-Source Voltage



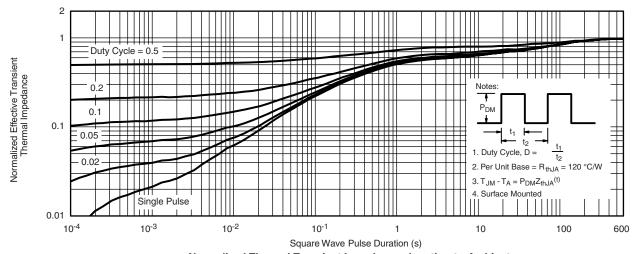


\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

Safe Operating Area



## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?73238">www.vishay.com/ppg?73238</a>.



# SOT-23 (TO-236): 3-LEAD







Dim	MILLIN	METERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A <sub>1</sub>	0.01	0.10	0.0004	0.004	
A <sub>2</sub>	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E <sub>1</sub>	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e <sub>1</sub>	1.90 BSC		0.074	0.0748 Ref	
L	0.40	0.60	0.016	0.024	
L <sub>1</sub>	0.64 Ref		0.025	0.025 Ref	
S	0.50 Ref		0.020	) Ref	
q	3°	8°	3°	8°	

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## **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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